



High-frequency switch IGBT Module 1200V / 100A

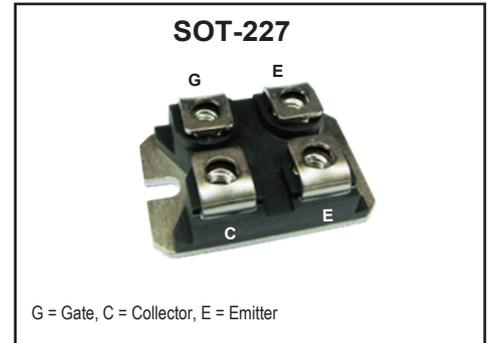
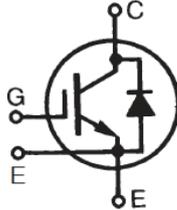
Features

- ◆ Fast Switching Trench / Field Stop IGBT Technology
- ◆ Low Switching Losses
- ◆ Super Fast Diodes
- ◆ High Short Circuit Capability

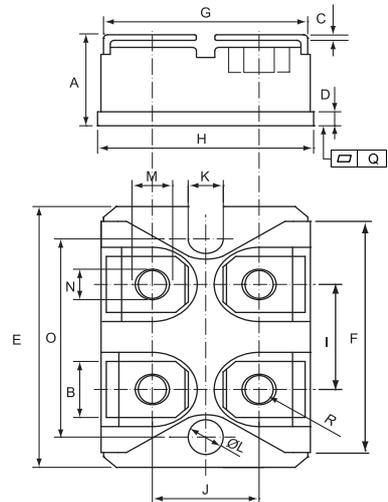
Applications

- ◆ Welder / Power Supply
- ◆ UPS / Inverter
- ◆ Industrial Motor Drive

Preliminary



Dimensions in inches and (millimeters)



Maximum Ratings (T_c = 25°C)

Item	Symbol	Rated Value	Unit
Collector-Emitter Voltage	V _{CEs}	1200	V
Gate-Emitter Voltage	V _{GES}	±20	V
DC-Collector Current	T _c = 80°C I _{C,nom.}	100	A
Repetitive Peak Collector Current	tp = 1ms I _{CRM}	200	A
Total Power Dissipation	P _{tot}	625	W
Isolation Voltage (A.C. 1 minute) between All Terminals and Baseplate	V _{iso}	2500	V
DC Forward Current	I _F	100	A
Repetitive Peak Forward Current	tp = 1ms I _{FRM}	200	A
Junction Temperature Range	T _J	-40~+150	°C
Storage Temperature Range	T _{stg}	-40~+125	°C
Mounting Torque (M4 screw)	To heatsink To terminals M _d	1.3 1.1	N.m
Weight		31	g

	DIMENSIONS			
	INCHES		MM	
	MIN	MAX	MIN	MAX
A	0.460	0.483	11.68	12.28
B	0.307	0.323	7.80	8.20
C	0.030	0.033	0.75	0.85
D	0.071	0.081	1.80	2.05
E	1.488	1.504	37.80	38.20
F	1.248	1.260	31.70	32.00
G	0.917	0.957	23.30	24.30
H	0.996	1.008	25.30	25.60
I	0.579	0.602	14.70	15.30
J	0.492	0.516	12.50	13.10
K	0.161	0.169	4.10	4.30
L	0.161	0.169	4.10	4.30
M	0.181	0.197	4.60	5.00
N	0.165	0.181	4.20	4.60
O	1.181	1.197	30.00	30.40
Q	-0.002	0.004	-0.05	0.10
R	M4*8			



■ Electrical Characteristics (T_c = 25°C)

Characteristic		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Collector-Emitter Cut-Off Current		I _{CES}	V _{CE} = 1200V V _{GE} = 0V	-	10	500	μA
Gate-Emitter Leakage Current		I _{GES}	V _{GE} = 20V V _{CE} = 0V	-	-	400	nA
Collector-Emitter Saturation Voltage		V _{CE(sat)}	I _C = 100A, V _{GE} = 15V	-	1.90	2.15	V
Gate-Emitter Threshold Voltage		V _{GE(th)}	V _{CE} = V _{GE} , I _C = 4mA	4.5	5.5	6.5	V
Input Capacitance		C _{ies}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz	-	15	-	nF
Output Capacitance		C _{oes}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz	-	0.40	-	nF
Reverse Transfer Capacitance		C _{res}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz	-	0.20	-	nF
Switching Time	Rise Time	t _r	V _{CC} = 600V I _C = 100A R _G = 1Ω V _{GE} = ±15V	-	0.04	-	μs
	Turn-On Time	t _{d,on}		-	0.16	-	
	Fall Time	t _f		-	0.08	-	
	Turn-Off Time	t _{d,off}		-	0.30	-	
Turn-on Energy Loss Per Pulse		E _{on}	I _C = 100A, V _{CC} = 600V V _{GE} = 15V, R _G = 1Ω	-	1.5	-	mJ
Turn-off Energy Loss Per Pulse		E _{off}	Inductive load	-	6.2	-	mJ
External Gate Resistance		R _G	Per Switch	1	-	10	Ω

■ Free Wheeling Diode Ratings & Characteristics (T_c = 25°C)

Characteristic		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Peak Forward Voltage		V _F	I _F = 100A, V _{GE} = 0V	-	1.8	2.3	V
Peak Reverse Recovery Current		I _{RM}	I _F = 100A, R _G = 1Ω V _R = 600V, V _{GE} = -15V	-	90	-	A
Recovered Charge		Q _r	I _F = 100A, R _G = 1Ω V _R = 600V, V _{GE} = -15V	-	9.9	-	μC
Reverse Recovery Energy		E _{rec}	I _F = 100A, R _G = 1Ω V _R = 600V, V _{GE} = -15V	-	6.25	-	mJ
Reverse Recovery Time		T _{rr}	I _F = 100A, R _G = 1Ω V _R = 600V, V _{GE} = -15V	-	142	-	ns

■ Thermal Characteristics (T_c = 25°C)

Characteristic		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Thermal Impedance	IGBT	R _{th(j-c)}	Junction to Case	-	-	0.20	°C/W
	Diode			-	-	0.48	



Typical Characteristics

Preliminary Data

Fig.1 Output characteristic (Typical)

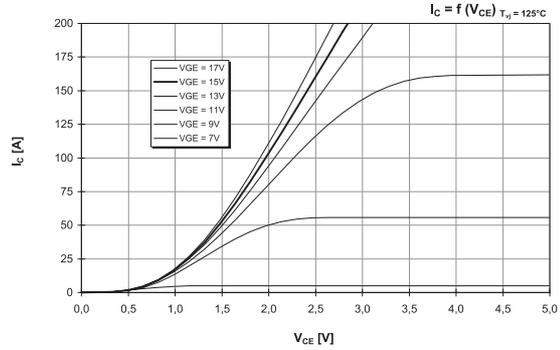
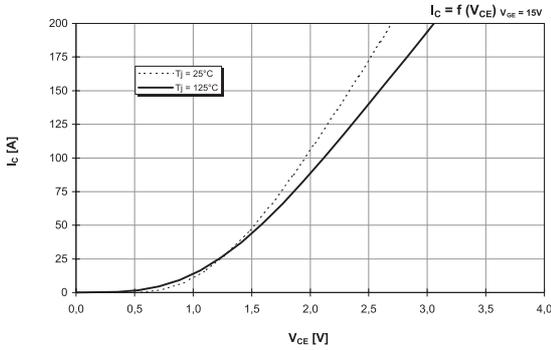


Fig.2 Transfer characteristic (Typical)

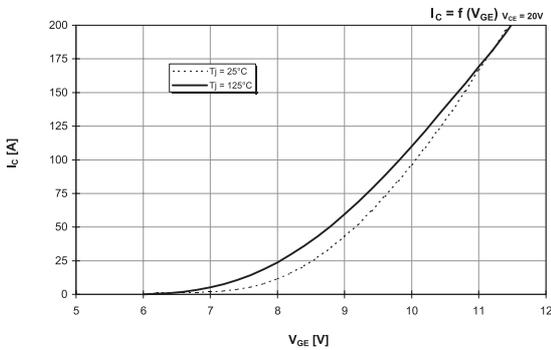


Fig.3 Forward characteristic of inverse diode (typical)

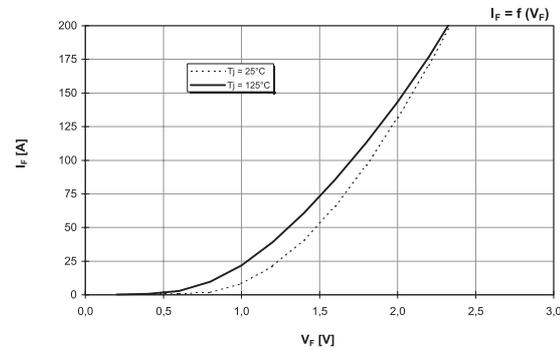


Fig.4 Switching losses (Typical)

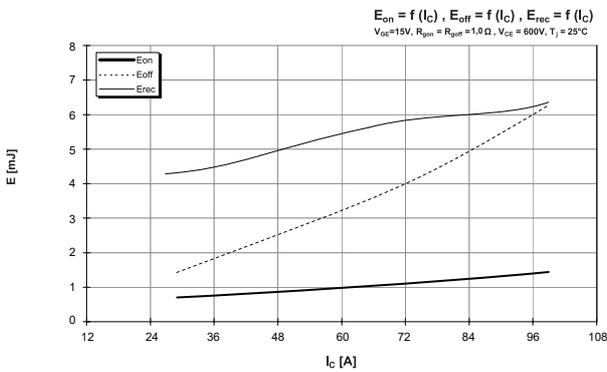


Fig.5 Switching losses IGBT, Inverter (typical)

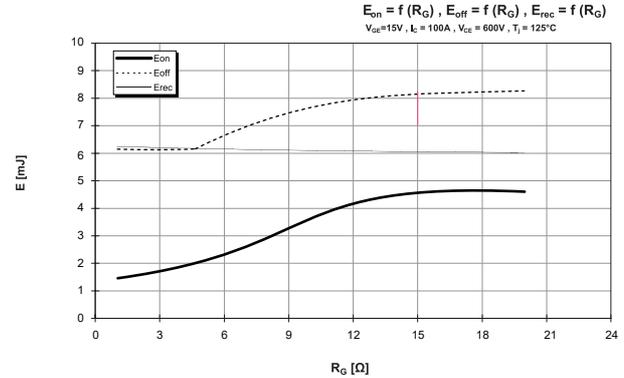
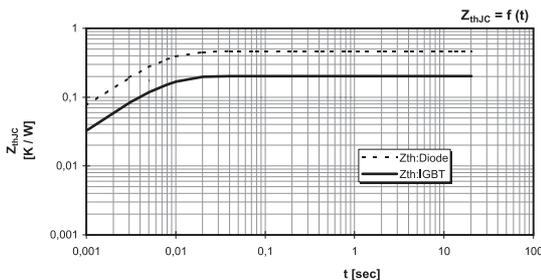
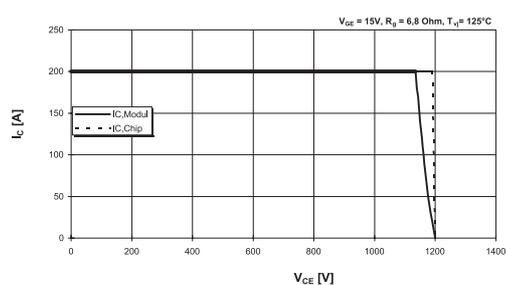


Fig.6 Transient thermal impedance



i	1	2	3	4
r_{θ} [K/kW] : IGBT	71.26	54.24	34.43	0.06
τ_i [sec] : IGBT	0.006	0.029	0.043	1.014
r_{θ} [K/kW] : Diode	81.89	122.02	63.19	32.9
τ_i [sec] : Diode	0.006	0.035	0.033	0.997

Fig.7 Reverse bias safe operation area (RBSOA)





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